Product/Process Change Notice - PCN 11_0072 Rev. B

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: ADG804 Wafer Fab location Transfer

Publication Date: 28-Oct-2011

Effectivity Date: 08-Aug-2011 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Removing ADG836 and ADG836L

Description Of Change

Wafer fabrication of the ADG804 product from 8" 0.35um CMOS process in Taiwan Semiconductor Manufacturing Company (TSMC) Fab no. 7A to the identical 8" 0.35um CMOS process TSMC Fab. no. 11. in Camas, USA.

PCN Revision A: ADG804 - As a result of the wafer fab transfer it is necessary to change switch leakage specification from 1nA at 25C to 2nA at 25C with revised test voltage bias conditions.

PCN Revision B - ADG836 and ADG836L devices have been removed from the fab transfer list. Specification changes identified in Rev A for the ADG836/L no longer apply.

Reason For Change

Increased wafer fabrication capacity

Impact of the change (positive or negative) on fit, form, function & reliability

With the exception of the switch leakage spec change outlined above there will be no impact on the form, fit, function, quality or reliability of the product.

Product Identification *(this section will describe how to identify the changed material)*

The ADG804 change over date code for TSMC Fab 11 is 1113.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Reliability Report.
Rev. A of the ADG804 Data Sheet will incorporate the above switch leakage specification changes.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_11_0072_Rev_B_Qualification_Data.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (4)			
ADG804 / ADG804YRM	ADG804 / ADG804YRMZ	ADG804 / ADG804YRMZ-REEL	ADG804 / ADG804YRMZ-REEL7

Removed Parts On All Revisions - Product Family / Model Number (13)				
ADG836 / ADG836YCPZ-REEL	ADG836 / ADG836YCPZ-REEL7	ADG836 / ADG836YRM	ADG836 / ADG836YRM-REEL	ADG836 / ADG836YRM-REEL7
ADG836 / ADG836YRMZ	ADG836 / ADG836YRMZ-REEL	ADG836 / ADG836YRMZ-REEL7	ADG836L / ADG836LYRM	ADG836L / ADG836LYRM-REEL
ADG836L / ADG836LYRM-REEL7	ADG836L / ADG836LYRMZ	ADG836L / ADG836LYRMZ-REEL7		

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	04-Apr-2011	Initial Release
Rev. A	08-Aug-2011	ADG804 and ADG836L Switch Leakage Specification Change
Rev. B	28-Oct-2011	Removing ADG836 and ADG836L